

CLEAN VERSION OF AMENDED SPECIFICATION PARAGRAPHS

METHOD FOR ATTACHING A SEMICONDUCTOR DIE TO A SUBSTRATE

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Serial No.: 09/649,827

Paragraph beginning on page 10, line 9:

The adhesive layer(s) 46, 48 may be responsive to heat, pressure, or both. In one embodiment, the heat responsive component is a thermosetting material. The thermosetting material may be a "B-stageable" material (i.e., having an intermediate stage in which the material remains wholly or partially plastic and fusible so that it softens when heated). In yet another embodiment, the heat responsive component is a thermoplastic material.